

Rigid-flex Circuits Capabilities			
No.	Item	Technical Data	
1	Layer Count	2~16Layers(Specialized in 4 & 6 layer)	
2	Min. Line Width/Space	2/2mil	
3	Max. panel size	600*800mm	
4	Edge of Coverlay Opening to Trace	0.20mm(preferred)	
5	Min Space between coverlay and solder pad	0.15mm	
6	Polyimide Films	0.5 mil (12.5 μ), 1 mil (25 μ), 2 mils (50 μ), 3 mils (75 μ), 4mils(100 μ), 5 mils(125 μ) as customer requested	
7	Thermabond Adhesive	Acrylic/Modified Acrylic, Modified Epoxy, Polyimide	
8	Copper Foils (RA or ED)	1/4oz to 3oz	
9	FR-4 in Multi-layer Flex Circuits	Laminated to flex circuit to create rigid flex boards, typically with vias	
10	Stiffeners	Polyimide, Rigid FR4, PSA, metal, or customer requested	
11	Solder Resist	Coverlay, LPI	
12	Min. Finished Hole size	0.2mm	
13	Max. Finished Hole size	6.30mm	
14	Hole tolerance	± 0.05 mm	
15	Min.space between holes	0.15mm	
16	Minimum conductor edge to outline edge	≥ 0.1 mm	
17	Minimum space between coverlay and conductor	± 0.15 mm	
18	Hole to outline edge	≥ 0.10 mm	
19	Tooling tolerance	Knife(Soft) tooling	± 0.25 mm
		Steel(Hard) tooling	± 0.05 mm
		CNC drill/rout	± 0.10 mm
20	Maximum Layer to Layer Mis-registration	± 0.10 mm	

21	Copper Plated Thickness (PTH only)	8~15um;20~30um;30~70um(special)
22	Surface Finish	Immersion Gold, HASL, Lead free HASL, Plating Hard Gold, OSP